



Docket No.: 275749US6PCT

OBLON
SPIVAK
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- &
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P.C.

ATTORNEYS AT LAW

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

RE: Application Serial No.: 10/018,837

Applicants: Motoki KATO, et al.

Filing Date: May 21, 2002

For: INFORMATION PROCESSING APPARATUS AND

METHOD, RECORDED MEDIUM, AND PROGRAM

Group Art Unit: 2616

Examiner: GROODY, JAMES J

SIR:

Attached hereto for filing are the following papers:

General Power of Attorney
Statement under 37 C.F.R. § 3.73(b)
Assignment (copy)

Our check in the amount of \$0.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Bradley D. Lytle

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GENERAL POWER OF ATTORNEY TO PROSECUTE APPLICATIONS BEFORE THE UNITED STATES PATENT AND TRADEMARK OFFICE

I hereby an	·	22050	\neg	
Practit	ioners associated with the Customer Number	22850		
as attorney(s) or agent(s) to represent the undersigned before the United States Patent and Trademark Office (USPTO) in connection with any and all patent applications assigned only to the undersigned according to the USPTO assignment records or assignment documents attached to this form in accordance with 37 CFR 3.73(b).				
Assignee N	Name and Address:		-	
Sony Corporation 6-7-35 Kitashinagawa, Shinagawa-ku, Tokyo, 141-0001 Japan				
A statement under 37 CFR 3.73(b) is attached.				
SIGNATURE OF ASSIGNEE OF RECORD The individual whose signature and title is supplied below is authorized to act on behalf of the assignee				
Signature	Kaichi Wade	D	ate: July 21,2005	
Name	Koichi Wada	T	elephone: 81-3-5435-3910	
Title	Manager, Intellectual Property Di	iv.		



STATEMENT UNDER 37 CFR 3.73(b)

Applicant/Patent Owner: Motoki KATO, et al.	
Application No./Patent No.: 10/018,837	Filed/Issue Date: May 21, 2002
Entitled: INFORMATION PROCESSING APPARATUS AND	METHOD, RECORDED MEDIUM, AND PROGRAM
	rporation ype of Assignee, e.g., corporation, partnership, government agency, etc.)
	ype of Assignee, e.g., corporation, partiership, government egonoy, etc.,
States that it is:	
1. the assignee of the entire right, title, and interest; or	
2. an assignee of less than the entire right, title and interest	st.
The extent (by, percentage) of its ownership interest is	%
in the patent application/patent identified above by virtue of an a application/patent identified above. A copy of the assignment is	assignment from the inventor(s) of the patent attached.
The undersigned (whose title is supplied below) is authorized to	act on behalf of the assignee.
Much	9/8/05
Signature	Date
Bradley D. Lytle	703-413-3000
Printed or Typed Name	Telephone Number
40,073	
Registration Number	

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

INFORMATION PROCESSING METHOD AND APPARATUS, RECORDING MEDIUM AND PROGRAM_

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/JP01/03418, International Filing Date: 20 April 2001.

This assignment executed on the dates indicated below.

Name of first or sole inventor Kanagawa, Japan Residence of first or sole inventor Mitoki hate Application Signature of first or sole inventor Date of this assignment Toshiya HAMADA Name of second inventor Saitama, Japan Residence of second inventor Toshiya Hamada Signature of second inventor Date of this assignment Execution date of U.S. Patent Application Date of this assignment Execution date of U.S. Patent Application Date of this assignment Date of this assignment Date of this assignment Date of third inventor Date of this assignment	Motoki KATO	
Residence of first or sole inventor Mitaki Fratt Signature of first or sole inventor Date of this assignment Toshiya HAMADA Name of second inventor Execution date of U.S. Patent Application Residence of second inventor Signature of second inventor Date of this assignment Date of this assignment Execution date of U.S. Patent Application Residence of third inventor Execution date of U.S. Patent Application Residence of third inventor	Name of first or sole inventor	Execution date of U.S. Patent Application
Signature of first or sole inventor Date of this assignment Toshiya HAMADA Name of second inventor Saitama, Japan Residence of second inventor Soshiya Hamada Signature of second inventor Date of this assignment Execution date of U.S. Patent Application Date of this assignment Execution date of U.S. Patent Application Execution date of U.S. Patent Application	Kanagawa, Japan	
Toshiya HAMADA Name of second inventor Saitama, Japan Residence of second inventor Joshiya Hamada Signature of second inventor Date of this assignment Name of third inventor Execution date of U.S. Patent Application Execution date of U.S. Patent Application		april 25, 2002
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Name of second inventor Saitama, Japan Residence of second inventor Signature of second inventor Date of this assignment Name of third inventor Residence of third inventor Execution date of U.S. Patent Application Execution date of U.S. Patent Application		
Saitama, Japan Residence of second inventor Joshiya Hanada Signature of second inventor Date of this assignment Name of third inventor Execution date of U.S. Patent Application Residence of third inventor	Toshiya HAMADA	
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Signature of second inventor Date of this assignment Execution date of U.S. Patent Application Residence of third inventor	Saitama, Japan	
Name of third inventor Execution date of U.S. Patent Application Residence of third inventor		April 25,2002
Residence of third inventor	Signature of second inventor	——············· ·- ·
Residence of third inventor		
	Name of third inventor	Execution date of U.S. Patent Application
Signature of third inventor Date of this assignment	Residence of third inventor	
	Signature of third inventor	Date of this assignment